

# **SOT23 TRANSISTOR(PNP)**

SOT23/TRANS(PNP)/-500mA/200-350

Rev1.0





## **SOT23 TRANSISTOR(PNP)**

#### 1.Features

- ◆ Complementary to S8050
- ◆ Power Dissipation of 300mW
- ◆ High Stability and High Reliability

#### 2. Mechanical Data

♦ SOT-23 Small Outline Plastic Package





#### 3. Maximum Ratings & Thermal Characteristics at Ta=25 $^{\circ}\mathrm{C}$

Parameter	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-25	V
Emitter -Base Voltage	$V_{EBO}$	-5	V
Collector Current-Continuous	lc	-500	mA
Collector Power Dissipation	Pc	300	mW
Junction Temperature	Tj	150	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +150	°C

#### 4.Electrical Characteristics at Ta=25°C

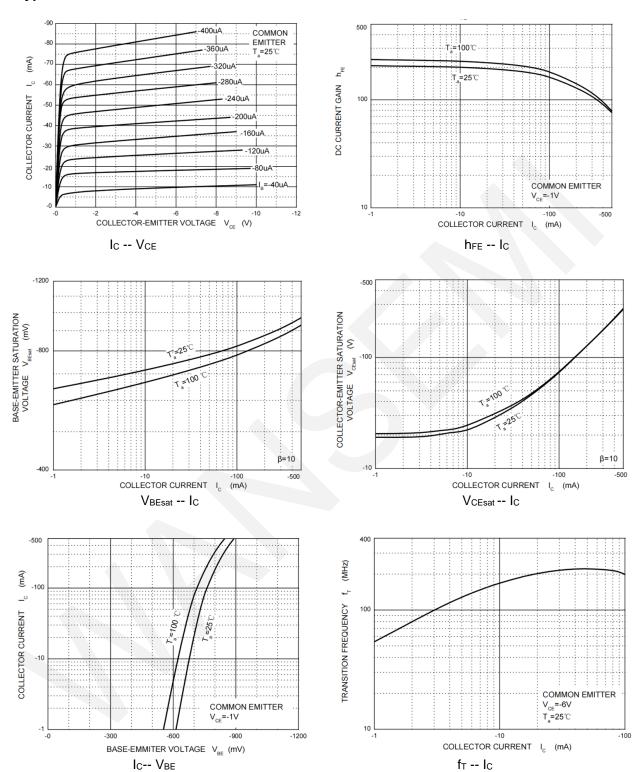
Parameter	Symbol	Test Conditions	Min.	Max.	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-100uA, I <sub>E</sub> =0	-50		V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =-1mA, I <sub>B</sub> =0	-30		>
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =-100uA, I <sub>C</sub> =0	-8		٧
Collector cut-off current	I <sub>CEO</sub>	V <sub>CE</sub> =-20V, I <sub>B</sub> =0		-100	nA
Collector cut-off current	Ісво	V <sub>CB</sub> =-40V, I <sub>E</sub> =0		-100	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =-4V, I <sub>C</sub> =0		-100	nA
DC comment rain	h <sub>FE(1)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-50mA	100	400	
DC current gain	h <sub>FE(2)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-500mA	50		
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =-500mA, I <sub>B</sub> =-50mA		-0.6	V
Base -emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =-500mA, I <sub>B</sub> =-50mA		-1.2	٧
Transition frequency	f⊤	V <sub>CE</sub> =-6V, I <sub>C</sub> =-20mA, f=30MHz	150		MHz

#### CLASSIFICATION OF $h_{\text{FE}(1)}$

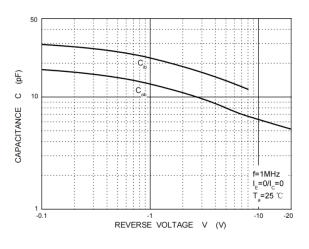
RANK	L	Н	J
RANGE	120-200	200-350	300-400

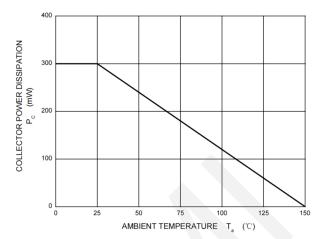


#### **5.Typical Characteristics**







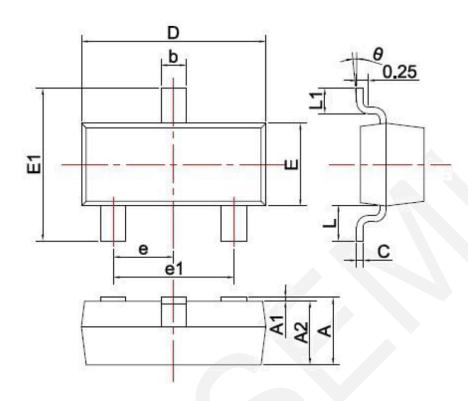


 $C_{ob}/C_{ib} - V_{CB}/V_{EB}$ 

P<sub>C</sub> -- T<sub>a</sub>



### 7.Package Dimensions



Symbol	Dimensions in Millimeters				
	MIN.	TYP.	MAX.		
А	0.900		1.150		
A1	0.000		0.100		
A2	0.900		1.050		
b	0.300		0.500		
С	0.080		0.150		
D	2.800		3.000		
E	1.200		1.400		
E1	2.250		2.550		
е		0.950			
e1	1.800		2.000		
L		0.550			
L1	0.300		0.500		
θ	0°		8°		



#### 8. Important Notice

WAN SEMICONDUCTOR (NINGBO) CO.,LTD reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services and to discontinue any product or service. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to WANSEMI's terms and conditions of sale supplied at the time of order acknowledgment.

WANSEMI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in WANSEMI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent WANSEMI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

WANSEMI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using WANSEMI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

No WANSEMI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Unless WANSEMI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use, WANSEMI will not be responsible for any failure of such components to meet such requirements.